Single Non-Inverting Buffer with Open Drain Output

The MC74VHC1G07 is an advanced high speed CMOS buffer with open drain output fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including a buffer and an open drain output which provides the capability to set the output switching level. This allows the MC74VHC1G07 to be used to interface any 2 V to 5.5 V circuit to circuits of any voltage between 1.5 V and 7 V using an external resistor and power supply.

The MC74VHC1G07 input structure provides protection when voltages up to 7 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 3.8 \text{ ns}$ (Typ) at $V_{CC} = 5 \text{ V}$
- Low Internal Power Dissipation: $I_{CC} = 1 \mu A \text{ (Max)}$ at $T_A = 25^{\circ}\text{C}$
- Power Down Protection Provided on Inputs
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FETs = 105
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

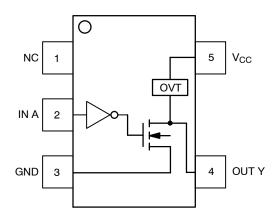


Figure 1. Pinout



Figure 2. Logic Symbol



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SC-88A / SOT-353 / SC-70 DF SUFFIX CASE 419A



MARKING



TSOP-5 / SOT-23 / SC-59 DT SUFFIX CASE 483



V7 = Device Code
M = Date Code*

• = Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

1	NC
2	IN A
3	GND
4	OUT Y
5	V _{CC}

FUNCTION TABLE

A Input	Y Output
L	L
П	Z

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V	
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current		-20	mA
lok	DC Output Diode Current	$V_{OUT} < GND; V_{OUT} > V_{CC}$	+20	mA
I _{OUT}	DC Output Sink Current, per Pin		+25	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pin		+50	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Secon	ds	260	°C
T_J	Junction Temperature Under Bias		+ 150	°C
θ_{JA}	Thermal Resistance S	SC70-5/SC-88A/SOT-353 (Note 1) SOT23-5/TSOP-5/SC59-5	350 230	°C/W
P _D	Power Dissipation in Still Air at 85°C	SC70-5/SC-88A/SOT-353 SOT23-5/TSOP-5/SC59-5	150 200	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I _{LATCHUP}	Latchup Performance Above V _{CC} a	and Below GND at 125°C (Note 5)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V _{CC}	DC Supply Voltage	2.0	5.5	V	
V _{IN}	DC Input Voltage	0.0	5.5	V	
V _{OUT}	DC Output Voltage	0.0	7.0	V	
T _A	Operating Temperature Range		- 55	+ 125	°C
t _r , t _f	Input Rise and Fall Time $ V_{CC} = 3.3 \text{ V} \pm \\ V_{CC} = 5.0 \text{ V} \pm $	0.3 V 0.5 V	0	100 20	ns/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

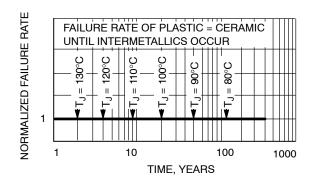


Figure 3. Failure Rate vs. Time Junction Temperature

DC ELECTRICAL CHARACTERISTICS

			V _{cc}	-	Γ _A = 25°	C	T _A ≤	85°C	-55°C ≤ 1	T _A ≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Minimum High-Level Input Voltage		2.0 3.0 4.5 5.5	1.5 2.1 3.15 3.85			1.5 2.1 3.15 3.85		1.5 2.1 3.15 3.85		V
V _{IL}	Maximum Low-Level Input Voltage		2.0 3.0 4.5 5.5			0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65	V
V _{OL}	Maximum Low-Level Output Voltage	$V_{IN} = V_{IL}$ $I_{OL} = 50 \mu A$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	٧
	$V_{IN} = V_{IH}$ or V_{IL}	$V_{IN} = V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I _{LKG}	Z-State Output Leakage Current	$V_{IN} = V_{IH}$ $V_{OUT} = V_{CC}$ or GND	5.5			±0.25		± 2.5		±5.0	μΑ
I _{IN}	Maximum Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I _{CC}	Maximum Quiescent Supply Current	V _{IN} = V _{CC} or GND	5.5			1.0		20		40	μΑ
I _{OFF}	Power Off-Output Leakage Current	V _{OUT} = 5.5 V V _{IN} = 5.5 V	0			0.25		2.5		5	μΑ

AC ELECTRICAL CHARACTERISTICS Input $t_f = t_f = 3.0 \text{ ns}$

			1	T _A = 25°C		T _A ≤	85°C	-55°C ≤ 1	A ≤ 125°C	
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PZL}	Maximum Output Enable Time, Input A to ₹	$\begin{array}{cccccccccccccccccccccccccccccccccccc$		5.0 7.5	7.1 10.6		8.5 12.0		10.0 14.5	ns
		$\begin{array}{cccccccccccccccccccccccccccccccccccc$		3.8 5.3	5.5 7.5		6.5 8.5		8.0 10.0	
t _{PLZ}	Maximum Output Disable Time	$\begin{array}{c} \text{V}_{\text{CC}} = 3.3 \ \pm \ 0.3 \ \text{V} & \text{C}_{\text{L}} = 50 \ \text{pF} \\ \text{R}_{\text{L}} = \text{R}_{\text{I}} = 500 \ \Omega \end{array}$		7.5	10.6		12.0		14.5	ns
		$V_{CC} = 5.0 \pm 0.5 \text{ V}$ $C_L = 50 \text{ pF}$ $R_L = R_I = 500 \Omega$		5.3	7.5		8.5		10.0	
C _{IN}	Maximum Input Capacitance			4	10		10		10	pF
					Ty	/pical @) 25°C, V _{CC} =	5.0 V		
C _{PD}	Power Dissipation C	Capacitance (Note 6)						18		рF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

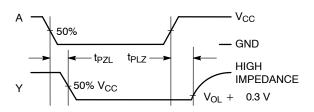
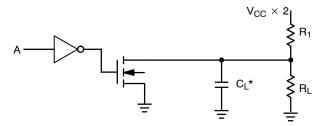


Figure 4. Switching Waveforms



*Includes jig and probe capacitance. $R_L = R_1 = 500 \ \Omega$

Figure 5. Test Circuit

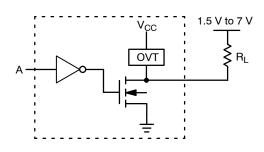


Figure 6. Output Voltage Mismatch Application

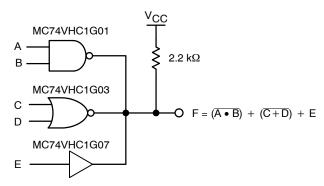


Figure 7. Complex Boolean Functions

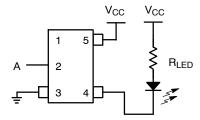


Figure 8. LED Driver

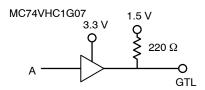


Figure 9. GTL Driver

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74VHC1G07DFT1G	SC70-5/SC-88A/SOT-353 (Pb-Free)	
NLVVHC1G07DFT1G*	SC70-5/SC-88A/SOT-353 (Pb-Free)	3000/Tape & Reel
MC74VHC1G07DFT2G	SC70-5/SC-88A/SOT-353 (Pb-Free)	Subul/Tape & neel
MC74VHC1G07DTT1G	SOT23-5/TSOP-5/SC59-5 (Pb-Free)	

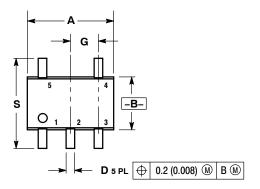
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

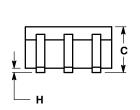
^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

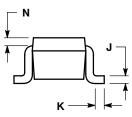
PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353)

CASE 419A-02 ISSUE L



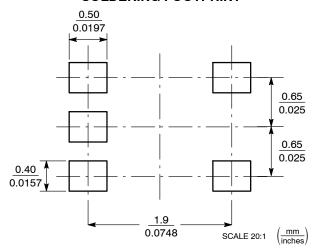




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

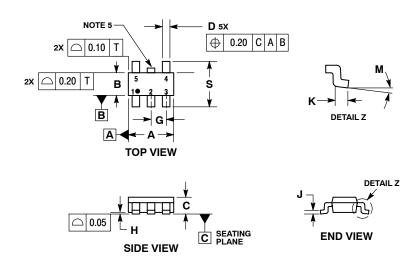
	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20	REF
S	0.079	0.087	2.00	2.20

SOLDERING FOOTPRINT



PACKAGE DIMENSIONS

TSOP-5 CASE 483-02 ISSUE K



NOTES:

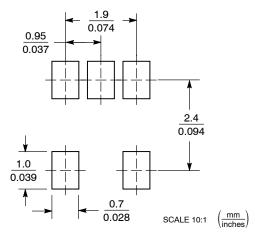
- DIMENSIONING AND TOLERANCING PER ASME
 V14 5M 1994
- Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- MINIMUM THICKNESS OF BASE MATERIAL.

 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.

 5. OPTIONAL CONSTRUCTION: AN ADDITIONAL
- OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

110111 BOB 11							
	MILLIMETERS						
DIM	MIN MAX						
Α	3.00	BSC					
В	1.50	BSC					
С	0.90	1.10					
D	0.25	0.50					
G	0.95	BSC					
Н	0.01	0.10					
J	0.10	0.26					
K	0.20	0.60					
М	0 °	10°					
S	2.50	3.00					

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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